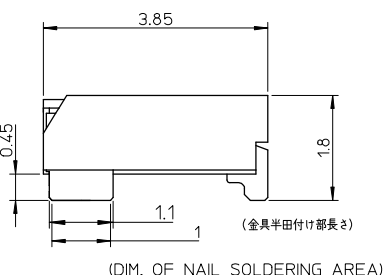
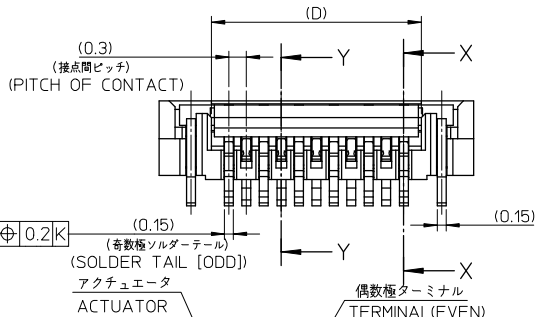
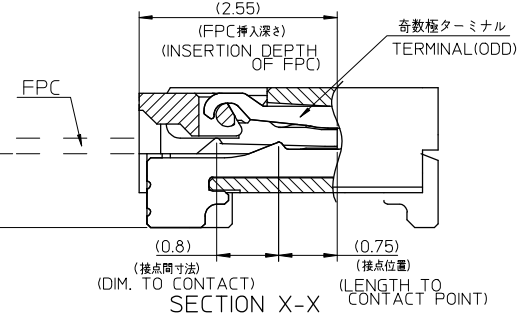
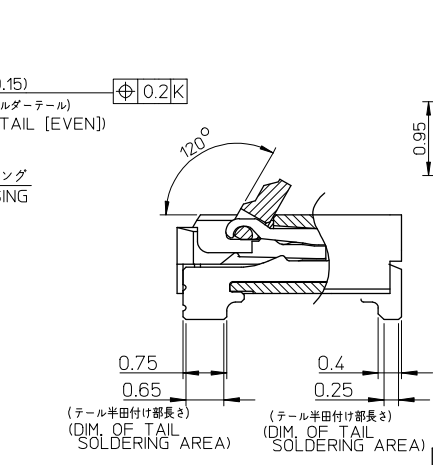
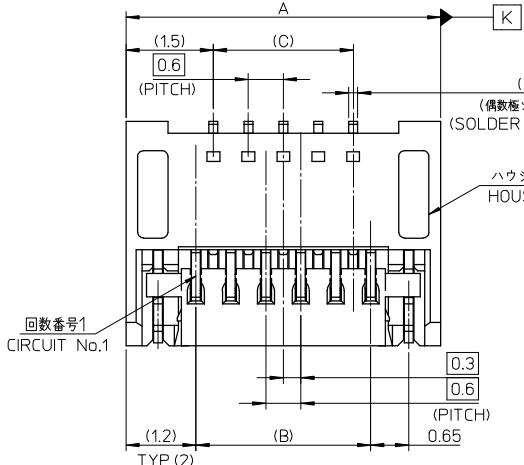
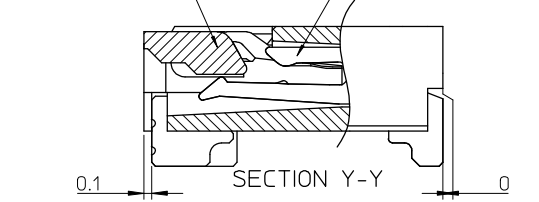


10 9 8 7 6 5 4 3 2 1



15.6	14.4	15.0	17.4	501912-5190	501912-5110	51
14.4	13.2	13.8	16.2	501912-4790	501912-4710	47
13.8	12.6	13.2	15.6	501912-4590	501912-4510	45
12.6	11.4	12.0	14.4	501912-4190	501912-4110	41
12.0	10.8	11.4	13.8	501912-3990	501912-3910	39
11.4	10.2	10.8	13.2	501912-3790	501912-3710	37
10.8	9.6	10.2	12.6	501912-3590	501912-3510	35
10.2	9.0	9.6	12.0	501912-3390	501912-3310	33
8.4	7.2	7.8	10.2	501912-2790	501912-2710	27
7.8	6.6	7.2	9.6	501912-2590	501912-2510	25
7.2	6.0	6.6	9.0	501912-2390	501912-2310	23
6.6	5.4	6.0	8.4	501912-2190	501912-2110	21
4.8	3.6	4.2	6.6	501912-1590	501912-1510	15

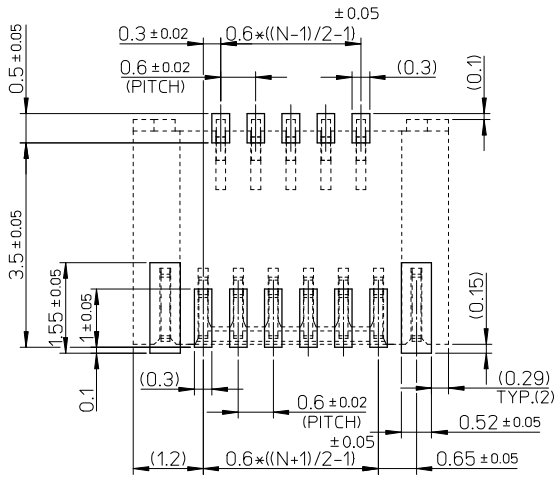


REVISED EC NO: J2008-3324 TIDRWNHTAGAMI 2008/03/25 CHYKDKTAKAHASHI 2008/04/07 APPR:KIKAKAHASHI 2008/04/07 REV DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	DRAWN BY M.HAYASHI	DATE 2005/07/28	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.8MM) GOLDPLATING			
	30 OVER ±0.3	ANGULAR ±3°	CHECKED BY H.HIRATA	DATE 2005/07/28	MOLEX INCORPORATED			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY M.SASAO	DATE 2005/07/28	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501912-001	SHEET NO. 1 OF 2	

lb\_frame\_A3\_J\_AM.S  
Rev. D 2004/06/28

EN-02DA(021)

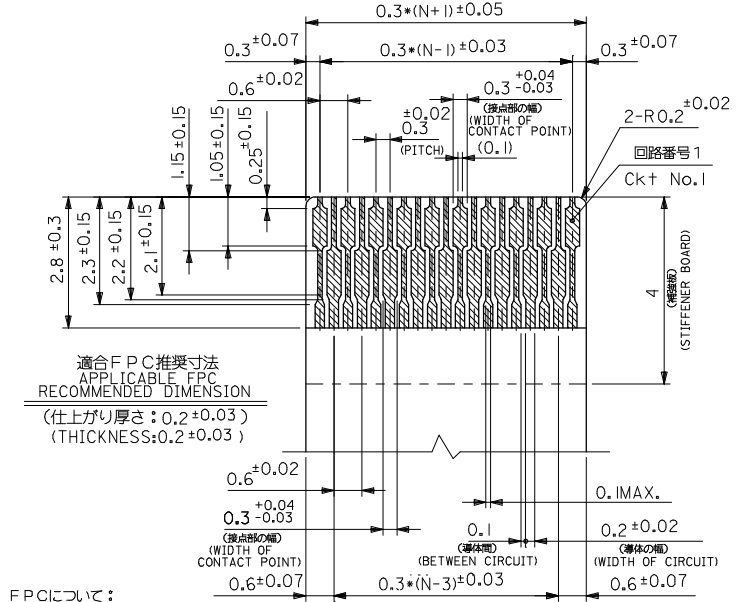
10 9 8 7 6 5 4 3 2 1



参考基板レイアウト図  
(マウント面)  
(MOUNTING SIDE)

注記 NOTES

- 使用材料 MATERIAL  
 ハウジング : 耐熱性樹脂 ガラス充填 UL94V-0  
 HOUSING : HEAT RESISTANCE POLYMER (GLASS FILLED) UL94V-0  
 アクチュエータ : 耐熱性樹脂 ガラス充填 UL94V-0  
 ACTUATOR : HEAT RESISTANCE POLYMER (GLASS FILLED) UL94V-0  
 ターミナル : 銅合金 (t=0.15), ニッケル下地金メッキ  
 TERMINAL : COPPER ALLOY, GOLD OVER NICKEL PLATING.  
 金具 : 銅合金 (t=0.15), ニッケル下地スメッキ  
 FITTING NAIL : COPPER ALLOY, TIN OVER NICKEL PLATING.  
 ハウジングに黒点がある場合が有りますが、問題はありません。
- ソルダーテール半田付け面、及び金具半田付け面の平坦度 : 0.1mm MAXIMUM.  
 COPLANARITY OF SOLDER TAILS AND FITTING NAILS TO BE 0.1mm MAXIMUM.
- ELV AND RoHS COMPLIANT.



適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION  
(仕上がり厚さ : 0.2 ± 0.03)  
(THICKNESS : 0.2 ± 0.03)

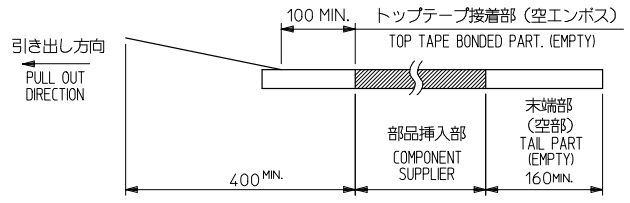
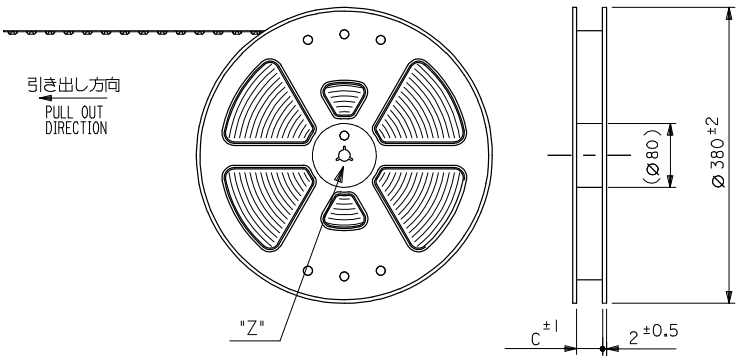
FPCについて:  
 打抜き方向は導体側から補強板側を推奨いたします。  
 導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを推奨致します。  
 補強フィルム材質はポリイミドを推奨します。  
 接着剤は熱硬化接着剤を推奨します。  
 ABOUT FPC  
 RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
 RECOMMENDED CONDUCTOR SPEC :  
 THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER  
 RECOMMENDED MATERIAL :  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2008-3324 TDRW:HTAGAMI 2008/03/25 CHKDK:TAKAHASHI 2008/04/07 APPR:K.TAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ----	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY M.HAYASHI	DATE 2005/07/28	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.8MM) GOLDPLATING	
	10 OVER 30 UNDER	± 0.25	CHECKED BY H.HIRATA	DATE 2005/07/28	MOLEX INCORPORATED	
	30 OVER	± 0.3	APPROVED BY M.SASAO	DATE 2005/07/28	DOCUMENT NO. SD-501912-001	SHEET NO. 2 OF 2
	ANGULAR ± 3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

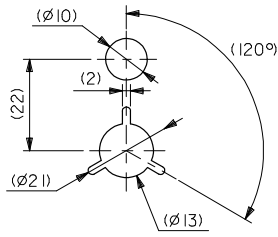
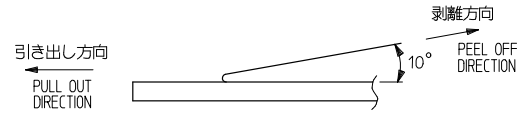
10 9 8 7 6 5 4 3 2 1

**NOTES**

1. 製品詳細寸法は製品単体図面を参照して下さい。  
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
2. 梱包数量 : 3000個/リール  
NUMBER OF CONNECTORS : 3000PCS/REEL
3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度 : 60±35gf (0.25N~0.93N) (剥離方向は下図参照) 尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)  
PEELING OFF FORCE OF TOP TAPE : 65gf±30gf (0.25N~0.93N) (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.) THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT. PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.

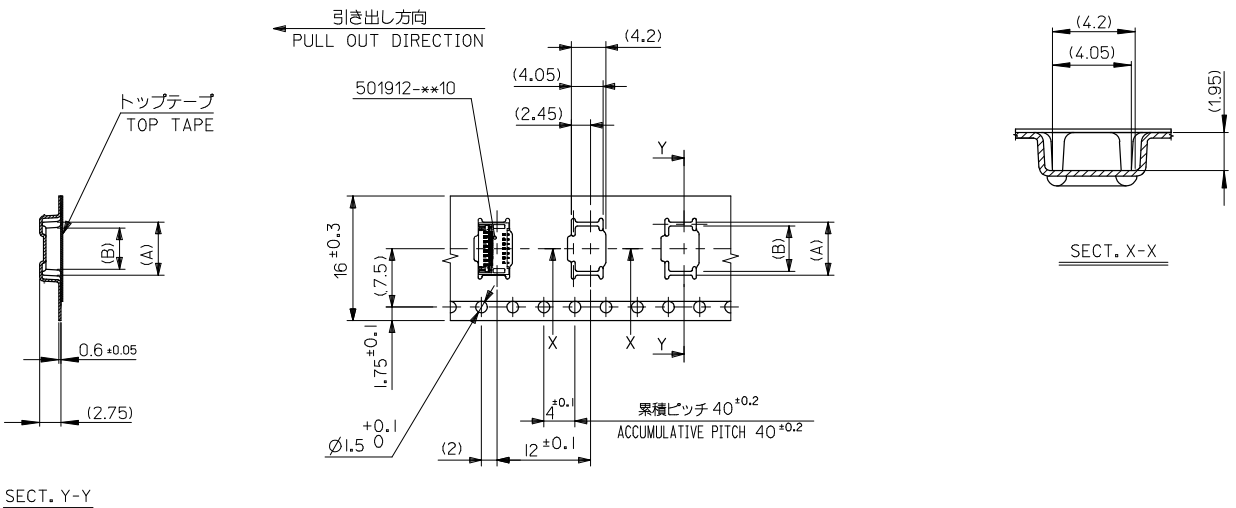


**DETAIL "Z"**

5. 材料(MATERIAL)  
キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYREN)  
トップテープ (TOP TAPE) : PET, PE, PEF  
リール (REEL) : ポリスチレン(PS) <リサイクル材を含む>  
POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>
6. C寸法は SHEET 2-4を参照下さい。  
SEE SHEET 2-4(DIMENSION C).
7. ELV AND RoHS COMPLIANT.

REVISED EC NO: J2008-3324 T: DRW: HTAGAMI 2008/03/25 CHK: K: TAKAHASHI 2008/04/07 APP: R: K: TAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 501912-***90
	10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING		
	10 OVER 30 UNDER	±0.25	CHECKED BY H. HIRATA	DATE 2005/10/11	THIRD ANGLE PROJECTION		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MOLEX INCORPORATED		
	ANGULAR ±3°	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-501912-002	SHEET NO. 1 OF 4		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

10 9 8 7 6 5 4 3 2 1

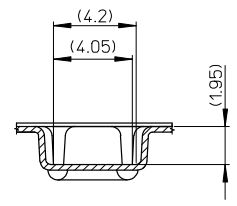
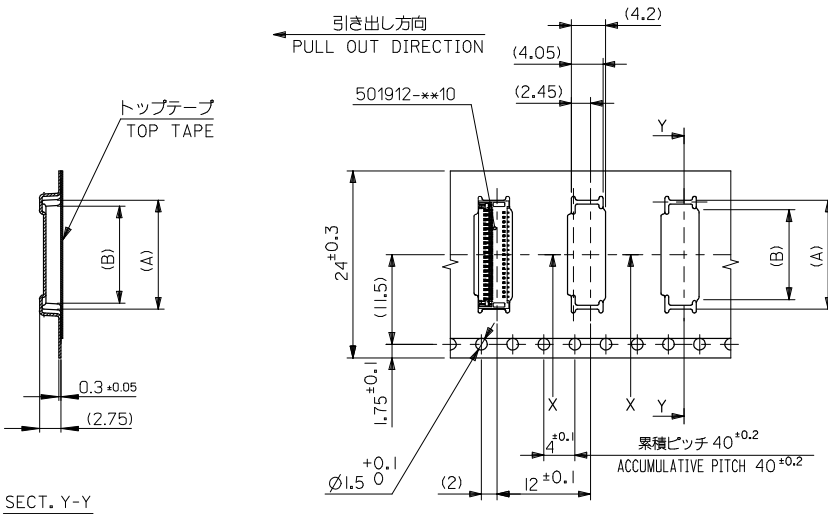


16 mm幅キャリアテープ  
16mm WIDTH CARRIER TAPE

16	17.5	4.6	6.8	501912-1590	15
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 CK+
				501912-**-**90	MODEL No.

REVISED EC NO: J2008-3324 T: DRW: H. TAGAMI 2008/03/25 CHYK: K. TAKAHASHI 2008/04/07 APPR: K. TAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± 0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING		
	10 OVER 30 UNDER	± 0.25	CHECKED BY H. HIRATA	DATE 2005/10/11	MOLEX INCORPORATED		
	30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501912-002	SHEET NO. 2 OF 4
	ANGULAR ± 3 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

10 9 8 7 6 5 4 3 2 1



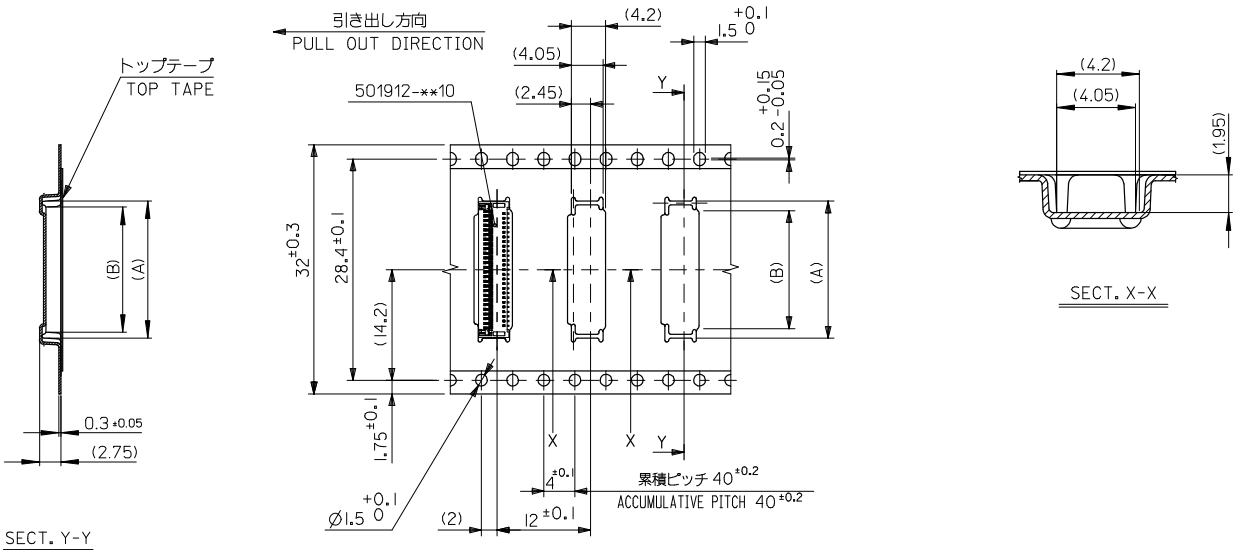
SECT. Y-Y

24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE

24	25.5	12.4	14.6	501912-4190	41
		11.8	14.0	501912-3990	39
		11.2	13.4	501912-3790	37
		10.6	12.8	501912-3590	35
		10.0	12.2	501912-3390	33
		8.2	10.4	501912-2790	27
		7.6	9.8	501912-2590	25
		7.0	9.2	501912-2390	23
6.4	8.6	501912-2190	21		
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 CK+

REVISED EC NO: J2008-3324 T: DRWN: H. TAGAMI 2008/03/25 CHYK: K. TAKAHASHI 2008/04/07 APPR: K. TAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING		
	10 OVER 30 UNDER	±0.25	CHECKED BY H. HIRATA	DATE 2005/10/11	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501912-002	SHEET NO. 3 OF 4
	ANGULAR ±3°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1



32mm幅キャリアテープ  
32mm WIDTH CARRIER TAPE

32	33.5	15.4	17.6	501912-5190	51
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	14.2	501912-4790	47
		(A)	13.6	501912-4590	45
				製品番号 MATERIAL No.	極数 CK+
				501912-**-90	MODEL No.

REVISED EC NO: J2008-3324 T: DRWN: HTAGAMI 2008/03/25 CHYK: K: TAKAHASHI 2008/04/07 APPR: K: TAKAHASHI 2008/04/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING		
	10 OVER 30 UNDER	±0.25	CHECKED BY H. HIRATA	DATE 2005/10/11	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501912-002	SHEET NO. 4 OF 4
	ANGULAR ±3°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		